L Number	Hits	Search Text	DB	Time stamp
1	233	257/666.ccls. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 11:39
2	198	(257/666.ccls. and laser) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:04
3	280	257/666.ccls. and (laser or (light adj emitting))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:02
5	12	((257/666.ccls. and (laser or (light adj emitting))) and (@ad<20020128)) and (light adj receiving)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 11:40
4	238	(257/666.ccls. and (laser or (light adj emitting))) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:08
6	362	257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:06
7	359	(257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)) not ((257/666.ccls. and (laser or (light adj emitting))) and (@ad<20020128))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 11:52
8	221	((257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)) not ((257/666.ccls. and (laser or (light adj emitting))) and (@ad<20020128))) and (lead or leads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 11:52
9	59646	(light adj (receiving or sensor)) and (laser or photodiode or (light adj (emitting or emitter)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:03
10	59647	(light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:04
11	53211	((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:04
12	1813	(((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)) and (encapsulant or encapsulate or mold or molding or epoxy) and (lead or leads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:07
13	262	257/100.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:06

14	75	257/80.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:06
15	103	257/79.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:06
16	0	(((((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)) and (encapsulant or encapsulate or mold or molding or epoxy) and (lead or leads)) and 385/$.ccls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:07
17	2041	((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and 385/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:07
18	249	(((((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)) and (encapsulant or encapsulate or mold or molding or epoxy) and (lead or leads)) and 385/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:08
19	244	((((((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)) and (encapsulant or encapsulate or mold or molding or epoxy) and (lead or leads)) and 385/$.ccls.) not (257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:08
20	244	((((((((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)) and (encapsulant or encapsulate or mold or molding or epoxy) and (lead or leads)) and 385/$.ccls.) not (257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128))) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:08